

Amendments to the Claims:

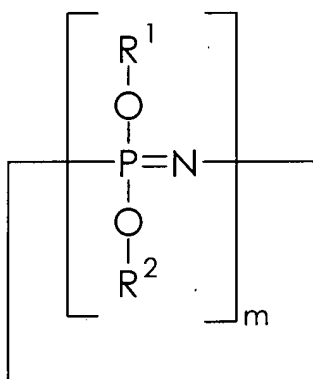
This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1.(original): A phosphazene compound, obtained by reacting a phenoxyphosphazene compound (A-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (A-2) obtained by cross-linking the phenoxyphosphazene compound (A-1) with an epoxy compound (B) having an unsaturated double bond and/or an isocyanate compound (C), wherein

the phosphazene compound has an unsaturated double bond in its molecule.

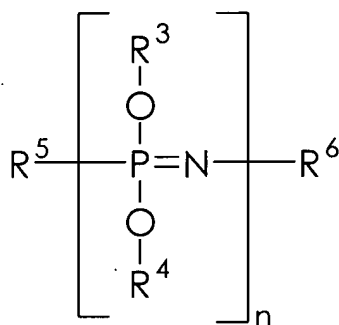
2.(original): The phosphazene compound as set forth in claim 1, wherein the phenoxyphosphazene compound (A-1) is a circular phenoxyphosphazene compound (A-11) represented by formula (1)



... (1)

where m represents an integer ranging from 3 to 25, and each of R¹ and R² represents a phenyl group or a hydroxyphenyl group, and a single molecule has one or more hydroxyphenyl groups.

3.(original): The phosphazene compound as set forth in claim 1, wherein the phenoxyphosphazene compound (A-1) is a chain phenoxyphosphazene compound (A-12) represented by formula (2)

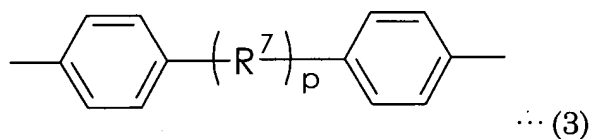


... (2)

where n represents an integer ranging from 3 to 10000, and each of R³ and R⁴ represents a phenyl group or a hydroxyphenyl group, and a single molecule has one or more hydroxyphenyl groups, and R⁵ represents -N=P(OC₆H₅)₃, -N=P(OC₆H₅)₂(OC₆H₄OH), -N=P(OC₆H₅)(OC₆H₄OH)₂, -N=P(OC₆H₄OH)₃, -N=P(O)OC₆H₅, or -N=P(O)(OC₆H₄OH), and R⁶ represents -P(OC₆H₅)₄, -P(OC₆H₅)₃(OC₆H₄OH), -P(OC₆H₅)₂(OC₆H₄OH)₂, -P(OC₆H₅)(OC₆H₄OH)₃, -P(OC₆H₄OH)₄, -P(O)(OC₆H₅)₂, -P(O)(OC₆H₅)(OC₆H₄OH), or -P(O)(OC₆H₄OH)₂.

4.(Currently Amended) The phosphazene compound as set forth in ~~any one of claims~~ claim 1 to 3, wherein the cross-linked phenoxyphosphazene compound (A-2) is obtained by cross-linking the phenoxyphosphazene compound (A-1) on the basis of a phenylene cross-linking group having at least one of an o-phenylene

group, a m-phenylene group, a p-phenylene group, and a bisphenylene group represented by formula (3)



where R⁷ represents -C(CH₃)₂-, -SO₂-, -S-, or -O-, and p represents 0 or 1.

5.(original): The phosphazene compound as set forth in claim 4, wherein

the cross-linked phenoxyphosphazene compound (A-2) is a phenylene cross-linked phenoxyphosphazene compound (A-3) in which

the circular phenoxyphosphazene compound (A-11) and/or the chain phenoxyphosphazene compound (A-12) is used as the phenoxyphosphazene compound, and

the phenylene cross-linking group intervenes between two oxygen atoms obtained by desorbing a phenyl group and a hydroxyphenyl group from the phenoxyphosphazene compound (A-1) so that a ratio at which the phenyl group and the hydroxyphenyl group are contained in the cross-linked phenoxyphosphazene compound ranges from 50 to 99.9 % with respect to a total of a phenyl group and a hydroxyphenyl group of the phenoxyphosphazene compound, the phenylene cross-linked phenoxyphosphazene compound (A-3) including at least one phenolic hydroxyl group.

6.(currently amended): A photosensitive resin composition, comprising at least the phosphazene compound as set forth in ~~any one of claims~~ claim 1 to 5 and a soluble polyimide resin (D) which is soluble in an organic solvent.

7.(original): The photosensitive resin composition as set forth in claim 6, further comprising a photoreaction initiator (E-1).

8.(currently amended): A photosensitive resin composition, comprising at least the phosphazene compound as set forth in ~~any one of claims~~ claim 1 ~~to 5~~ and a photoreaction initiator (E-1).

9.(currently amended): The photosensitive resin composition as set forth in ~~any one of claims~~ claim 6 ~~to 8~~, further comprising a compound having a carbon-carbon double bond (E-4).

10.(original): The photosensitive resin composition as set forth in claim 6, wherein 1 wt% or more of the soluble polyimide resin (D) is dissolved in at least one kind of an organic solvent selected from dioxolane, dioxane, tetrahydrofuran, N,N-dimethylformamide, N,N-dimethylacetamide, and N-methyl-2-pyrrolidone at temperature ranging from room temperature to 100°C.

11.(currently amended): A photosensitive resin film, being formed by using the photosensitive resin composition as set forth in ~~any one of claims~~ claim 6 ~~to 10~~.

12.(original): The photosensitive resin film as set forth in claim 11, being used as a print wiring board adhesive sheet, a photosensitive cover lay film, a print wiring insulative protection film, or a print wiring board substrate.

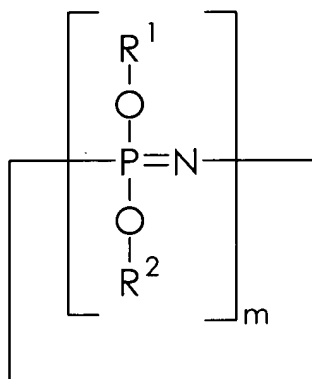
13.(original): A photosensitive resin composition having at least a polyimide resin (G) and a phosphazene compound (H),

said photosensitive resin composition comprising: a soluble polyimide resin (G-1), which has a carboxyl group and/or a hydroxyl group and is soluble in an organic solvent, as the polyimide resin (G); and

a phenoxyphosphazene compound (H-1) having a phenolic hydroxyl group and/or a cross-linked phenoxyphosphazene compound (H-2), which is obtained by cross-linking the phenoxyphosphazene compound (H-1) and has at least one phenolic hydroxyl group, as the phosphazene compound (H),

said photosensitive resin composition further comprising a (meth)acrylic compound (I).

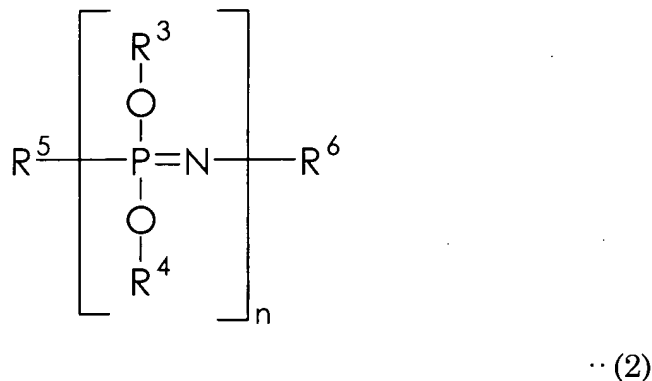
14.(original): The photosensitive resin composition as set forth in claim 13, wherein the phenoxyphosphazene compound (H-1) includes a circular phenoxyphosphazene compound (H-11) represented by formula (1)



... (1)

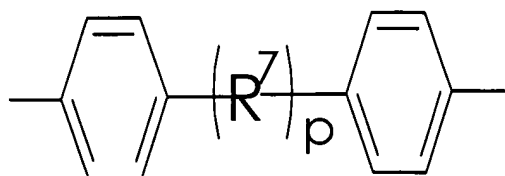
where m represents an integer ranging from 3 to 30, and each of R1 and R2 represents a phenyl group or a hydroxyphenyl group, and a single molecule has one or more hydroxyphenyl groups.

15.(original): The photosensitive resin composition as set forth in claim 13, wherein the phenoxyphosphazene compound (H-1) includes a chain phenoxyphosphazene compound (H-12) represented by formula (2)



where n represents an integer ranging from 3 to 10000, and each of R³ and R⁴ represents a phenyl group or a hydroxyphenyl group, and a single molecule has one or more hydroxyphenyl groups, and R⁵ represents -N=P(OC₆H₅)₃, -N=P(OC₆H₅)₂(OC₆H₄OH), -N=P(OC₆H₅)(OC₆H₄OH)₂, -N=P(OC₆H₄OH)₃, -N=P(O)OC₆H₅, or -N=P(O)(OC₆H₄OH), and R⁶ represents -P(OC₆H₅)₄, -P(OC₆H₅)₃(OC₆H₄OH), -P(OC₆H₅)₂(OC₆H₄OH)₂, -P(OC₆H₅)(OC₆H₄OH)₃, -P(OC₆H₄OH)₄, -P(O)(OC₆H₅)₂, -P(O)(OC₆H₅)(OC₆H₄OH), or -P(O)(OC₆H₄OH)₂.

16.(currently amended): The photosensitive resin composition as set forth in ~~any one of claims~~ claim 13 ~~to 15~~, wherein the cross-linked phenoxyphosphazene compound (H-2) is obtained by cross-linking the phenoxyphosphazene compound (H-1) on the basis of a phenylene cross-linking group having at least one of an o-phenylene group, a m-phenylene group, a p-phenylene group, and a bisphenylene group represented by formula (3)



... (3)

where R^7 represents $-C(CH_3)_2-$, $-SO_2-$, $-S-$, or $-O-$, and p represents 0 or 1.

17.(original): The photosensitive resin composition as set forth in claim 16, wherein the cross-linked phenoxyphosphazene compound (H-2) is a phenylene cross-linked phenoxyphosphazene compound (H-21) in which

the circular phenoxyphosphazene compound (H-11) and/or the chain phenoxyphosphazene compound (H-12) is used as the phenoxyphosphazene compound, and

the phenylene cross-linking group intervenes between two oxygen atoms obtained by desorbing a phenyl group and a hydroxyphenyl group from the phenoxyphosphazene compound (H-1) so that a ratio at which the phenyl group and the hydroxyphenyl group are contained in the cross-linked phenoxyphosphazene compound ranges from 50 to 99.9 % with respect to a total of a phenyl group and a hydroxyphenyl group of the phenoxyphosphazene compound, said phenylene cross-linked phenoxyphosphazene compound (H-21) including at least one phenolic hydroxyl group.

18.(currently amended): The photosensitive resin composition as set forth in ~~any one of claims~~ claim 13 to 17, wherein the soluble polyimide resin (G-1) has at least one kind of an unsaturated double bond selected from an acryl group, a methacryl group, a vinyl group, and an allyl group.

19.(currently amended): The photosensitive resin composition as set forth in ~~any one of claims~~ claim 13 to 18, wherein an amount of the phosphazene compound (H) ranges from 1 to 100 parts by weight with respect to 100 parts by weight corresponding to a total weight of the polyimide resins (G) and the (meth)acrylic compound (I).

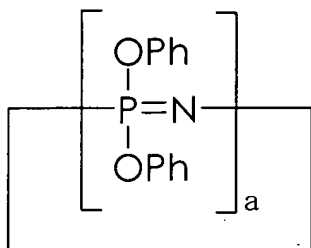
20.(currently amended): A photosensitive resin film, being formed by using the photosensitive resin composition as set forth in ~~any one of claims~~ claim 13 to 19.

21.(original): The photosensitive resin film as set forth in claim 20, wherein: in case of using 1 wt% of sodium hydroxide whose temperature is 40°C as a developer and using a spray developing device as developing means, dissolution time under a spray pressure of 0.85 MPa is 180 seconds or less.

22.(currently amended): The photosensitive resin film as set forth in claim 20 ~~or 21~~, being used as a pattern circuit resist film, a photosensitive cover lay film, or a photosensitive dry film resist.

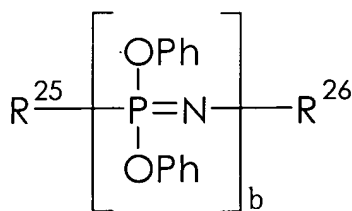
23.(original): A photosensitive resin composition, comprising a soluble polyimide resin (K) having a carboxyl group and/or a hydroxyl group, a phenoxyphosphazene compound (L), and a (meth)acrylic compound (M),

said phenoxyphosphazene compound (L) including at least one of a circular phenoxyphosphazene compound (L-1) represented by formula (22) and a chain phenoxyphosphazene compound (L-2) represented by formula (23),



... (22)

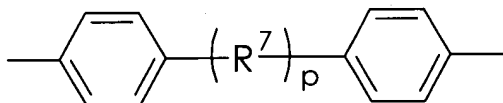
where a represents an integer ranging from 3 to 30,



... (23)

where R^{25} represents group- $\text{N}=\text{P}(\text{OPh})_3$ or group- $\text{N}=\text{P}(\text{O})\text{OPh}$, and R^{26} represents group- $\text{P}(\text{OPh})_4$ or group- $\text{P}(\text{O})(\text{OPh})_2$, and b represents an integer ranging from 3 to 10000, wherein

the phenoxyphosphazene compound (L) includes a cross-linked phenoxyphosphazene compound (L-3) having a structure cross-linked by causing a cross-linking group having any one of an o-phenylene group, an m-phenylene group, a p-phenylene group, and a bisphenylene group represented by formula (3) to intervene between two oxygen atoms obtained by desorbing a phenyl group,



... (3)

where R^7 represents $-\text{C}(\text{CH}_3)_2-$, $-\text{SO}_2-$, $-\text{S}-$, or $-\text{O}-$, and p represents 0 or 1.

24.(original): The photosensitive resin composition as set forth in claim 23, wherein a soluble polyimide resin serving as the component (K) has at least one kind of a carbon-carbon double bond selected from an acryl group, a methacryl group, a vinyl group, and an allyl group.

25.(currently amended): The photosensitive resin composition as set forth in claim 23 ~~or 24~~, wherein an amount of the component (L) ranges from 1 to 100 parts by weight with respect to 100 parts by weight corresponding to a total weight of the components (K) and (L).

26.(currently amended) A photosensitive dry film resist, produced by using the photosensitive resin composition as set forth in ~~any one of claims~~ claim 23 to ~~25~~.

27.(original): The photosensitive dry film resist as set forth in claim 26, wherein: in case of using 1 wt% of sodium hydroxide whose temperature is 40°C as a developer and using a spray developing device as developing means,

dissolution time under a spray pressure of 0.85 MPa is 180 seconds or less.

28.(currently amended): A print wiring board, using the photosensitive dry film resist as set forth in claim 26 ~~or 27~~ as an insulative protection layer.